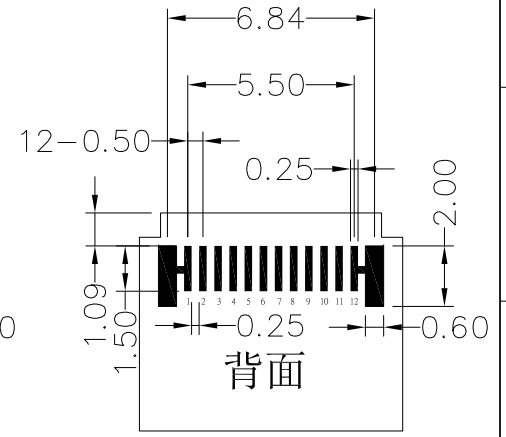
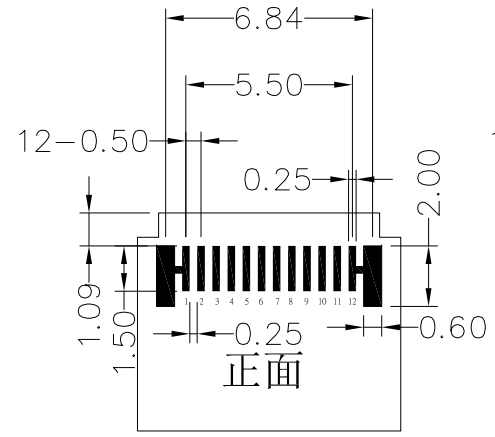
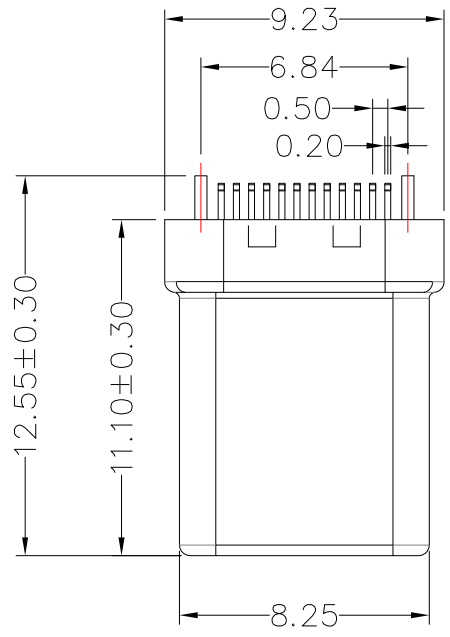




SBC-241PL26-31x-S271

鍍層厚度 :

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LATOUT

SPECIFICATIONS

Electrical:

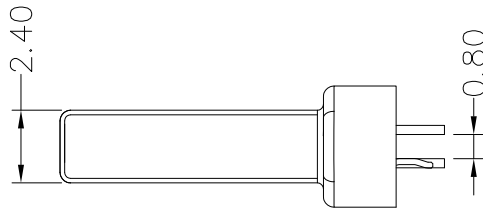
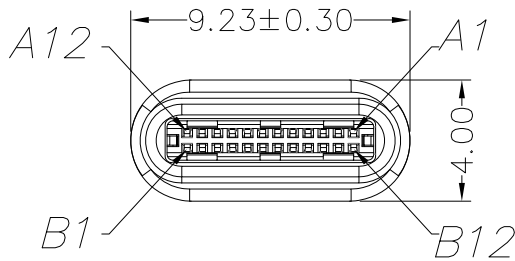
- 1.Current Rating: 0.5A
- 2.Contact Resistance: 30 mΩ Max
- 3.Dielectric Withstanding Voltage: 100 V AC
- 5.Insulation Resistance: 100 MΩ Min

Material:

- 1.Housing:LCP
- 2.Contact: C7025
- 3.Shell: SUS

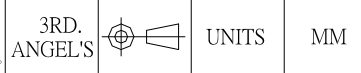
Finish:

- 1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer



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TOLERANCE-UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3



DRAWN BY:	DATE	MATL	TITLE	CONNECTOR
Jack Lu	11/18/22			
CHECKED BY:	DATE	FINISH	MODLE	TYPE C 公頭不帶板 拉伸款
Jacky Chen	11/18/22			
APPROVED BY:	DATE	SCALE	DWG NO.	SBC-241PL26-31x-S271
Tony Kao	11/18/22	1 : 1	PART NO.	SBC-241PL26-31x-S271
		SHEET NO.	1 of 1	
				SIZE A4
				VER R3

ITEM NO	DESCRIPTION	DRAWN	DATE
3	更新Contact材質	Jack	111822
2	更新尺寸	Jack	060820
1	更新PCB LAYOUT	Jack	123019